UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. : 7,061,785 B2
APPLICATION NO. : 10/606891
DATED : June 13, 2006
INVENTOR(S) : Takashi Miwa et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 14, after Claim 10, add the following claims:

11. A semiconductor device according to claim 7, wherein said first and second bonding leads include bonding leads having notched portions over which wires connected to other bonding leads pass.

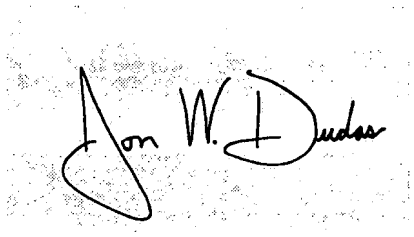
12. A semiconductor device according to claim 8,

wherein said first and second bonding leads are arranged in a staggered manner, each in two inner and outer rows along extension directions of wires which are connected thereto, and

wherein notched portions are formed at inner ends of bonding leads in said inner rows.

Signed and Sealed this

Eighth Day of May, 2007



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Director of the United States Patent and Trademark Office